

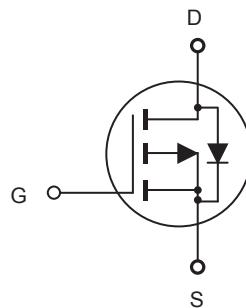


CED6601/CEU6601

P-Channel Enhancement Mode Field Effect Transistor

FEATURES

- -60V, -16A, $R_{DS(ON)} = 86m\Omega$ @ $V_{GS} = -10V$.
 $R_{DS(ON)} = 125m\Omega$ @ $V_{GS} = -4.5V$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- TO-251 & TO-252 package.



ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	-16	A
Drain Current-Pulsed ^a	I_{DM}	-64	A
Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above $25^\circ C$	P_D	43 0.29	W W/ $^\circ C$
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	R_{JC}	3.5	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	R_{JA}	50	$^\circ C/W$



CED6601/CEU6601

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -60\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics^b						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = -250\mu\text{A}$	-1		-3	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -8\text{A}$		61	86	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -6\text{A}$		75	125	$\text{m}\Omega$
Dynamic Characteristics^c						
Forward Transconductance	g_{FS}	$V_{\text{DS}} = -10\text{V}, I_D = -15\text{A}$		10		S
Input Capacitance	C_{iss}	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		1135		pF
Output Capacitance	C_{oss}			95		pF
Reverse Transfer Capacitance	C_{rss}			60		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -30\text{V}, I_D = -1\text{A}, V_{\text{GS}} = -10\text{V}, R_{\text{GEN}} = 6\Omega$		13	26	ns
Turn-On Rise Time	t_r			4	8	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			45	90	ns
Turn-Off Fall Time	t_f			6	12	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = -30\text{V}, I_D = -3.5\text{A}, V_{\text{GS}} = -10\text{V}$		22.6	29.4	nC
Gate-Source Charge	Q_{gs}			2.4		nC
Gate-Drain Charge	Q_{gd}			5.7		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				-16	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = -16\text{A}$			-1.5	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- c.Guaranteed by design, not subject to production testing.

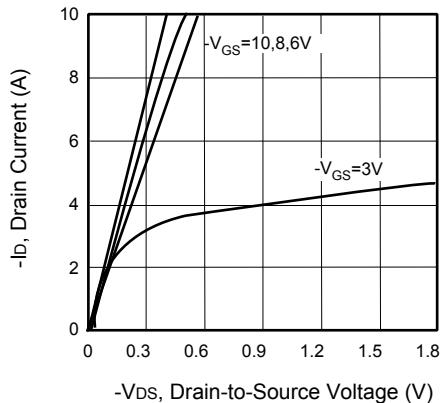


Figure 1. Output Characteristics

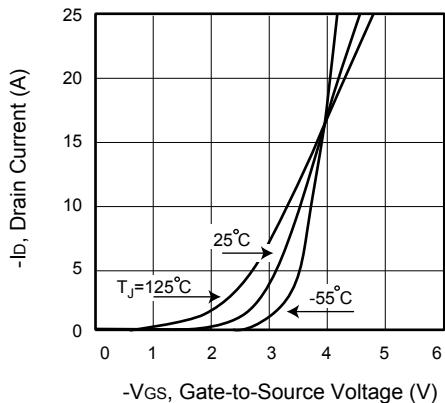


Figure 2. Transfer Characteristics

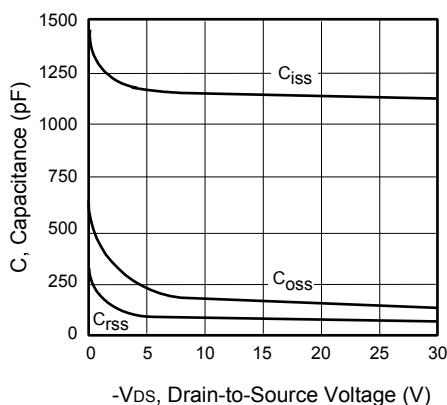


Figure 3. Capacitance

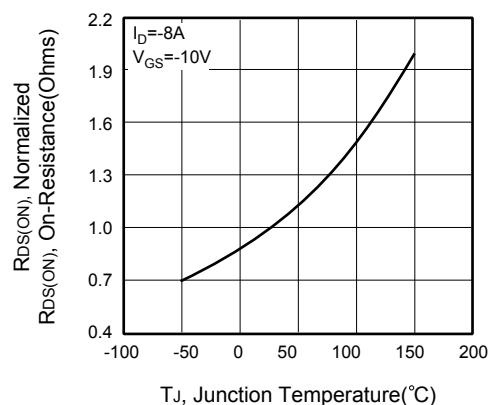


Figure 4. On-Resistance Variation with Temperature

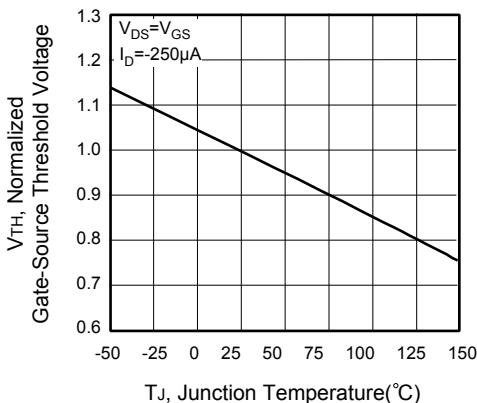


Figure 5. Gate Threshold Variation with Temperature

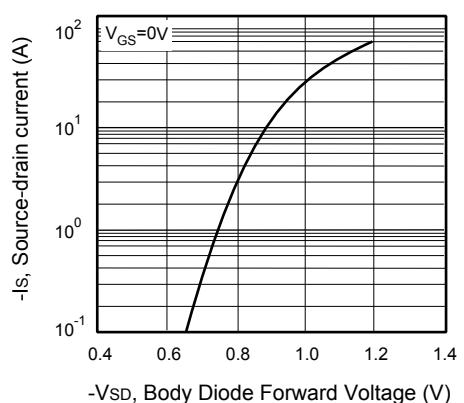


Figure 6. Body Diode Forward Voltage Variation with Source Current



CED6601/CEU6601

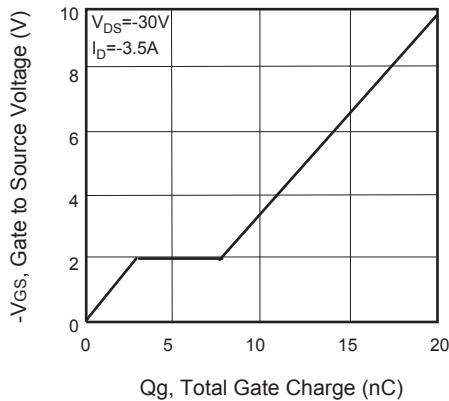


Figure 7. Gate Charge

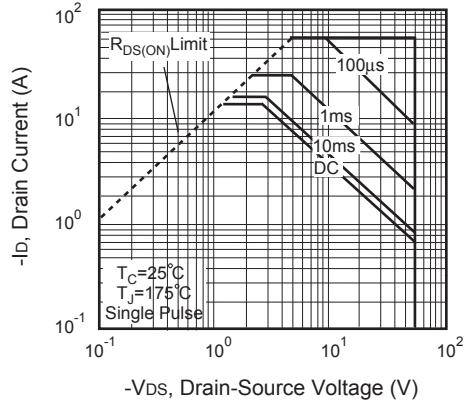


Figure 8. Maximum Safe Operating Area

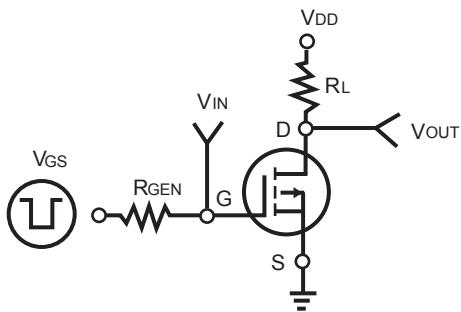


Figure 9. Switching Test Circuit



Figure 10. Switching Waveforms

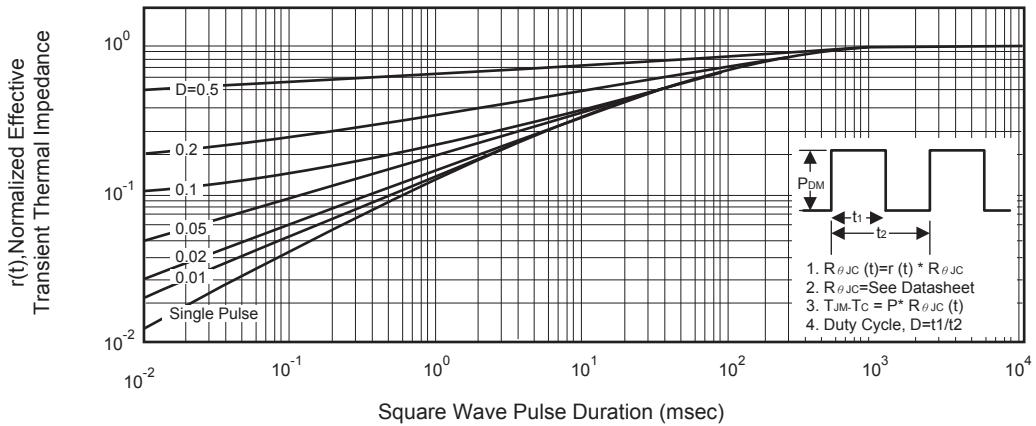


Figure 11. Normalized Thermal Transient Impedance Curve